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(12) **United States Design Patent**
Arakawa et al.

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(54) **SEMICONDUCTOR SUBSTRATE TRANSFER APPARATUS**

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(73) Assignee: **Hitachi High-Tech Corporation**, Tokyo (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/789,675**

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(30) **Foreign Application Priority Data**

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(51) **LOC (14) Cl.** **15-09**
(52) **U.S. Cl.**
USPC **D15/122**
(58) **Field of Classification Search**
USPC D13/118, 158, 162, 184; D15/122, 138, D15/141, 199
CPC H01L 21/70; H01L 21/67207; H01L 21/68742; H01L 21/67023
See application file for complete search history.

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(57) **CLAIM**

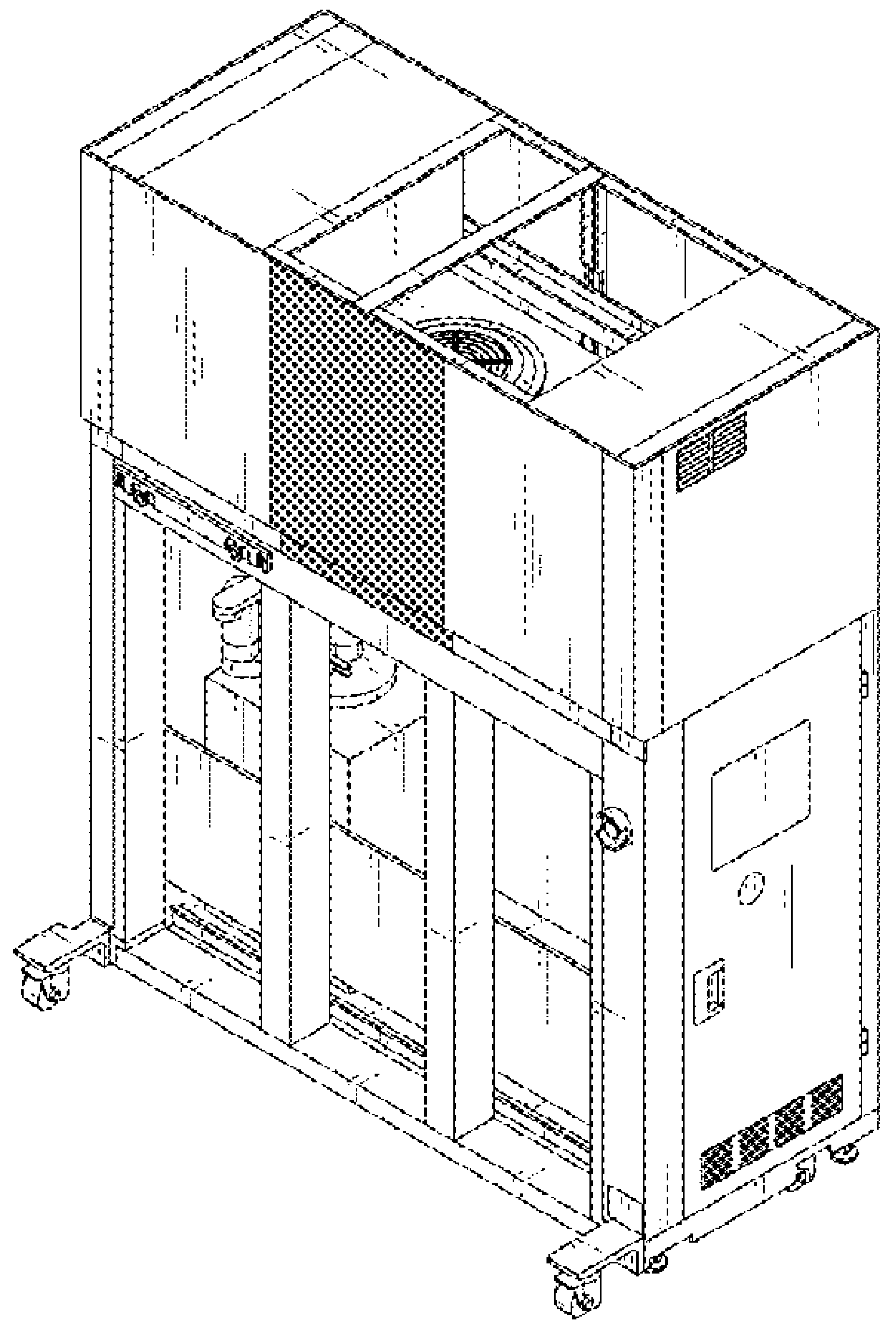
The ornamental design for a semiconductor substrate transfer apparatus, as shown and described.

DESCRIPTION

FIG. **1** is a front, top, and right side perspective view of a semiconductor substrate transfer apparatus according to the design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a left side elevational view thereof;
FIG. **5** is a right side elevational view thereof;
FIG. **6** is a top plan view thereof;
FIG. **7** is a bottom plan view thereof; and,
FIG. **8** is a cross-sectional view taken along line **8**-**8** of FIG. **2**.

The broken lines illustrate portions of the semiconductor substrate transfer apparatus that form no part of the claimed design. The hatching shown in FIG. **8** represents unclaimed subject matter and forms no part of the claimed design.

1 Claim, 7 Drawing Sheets



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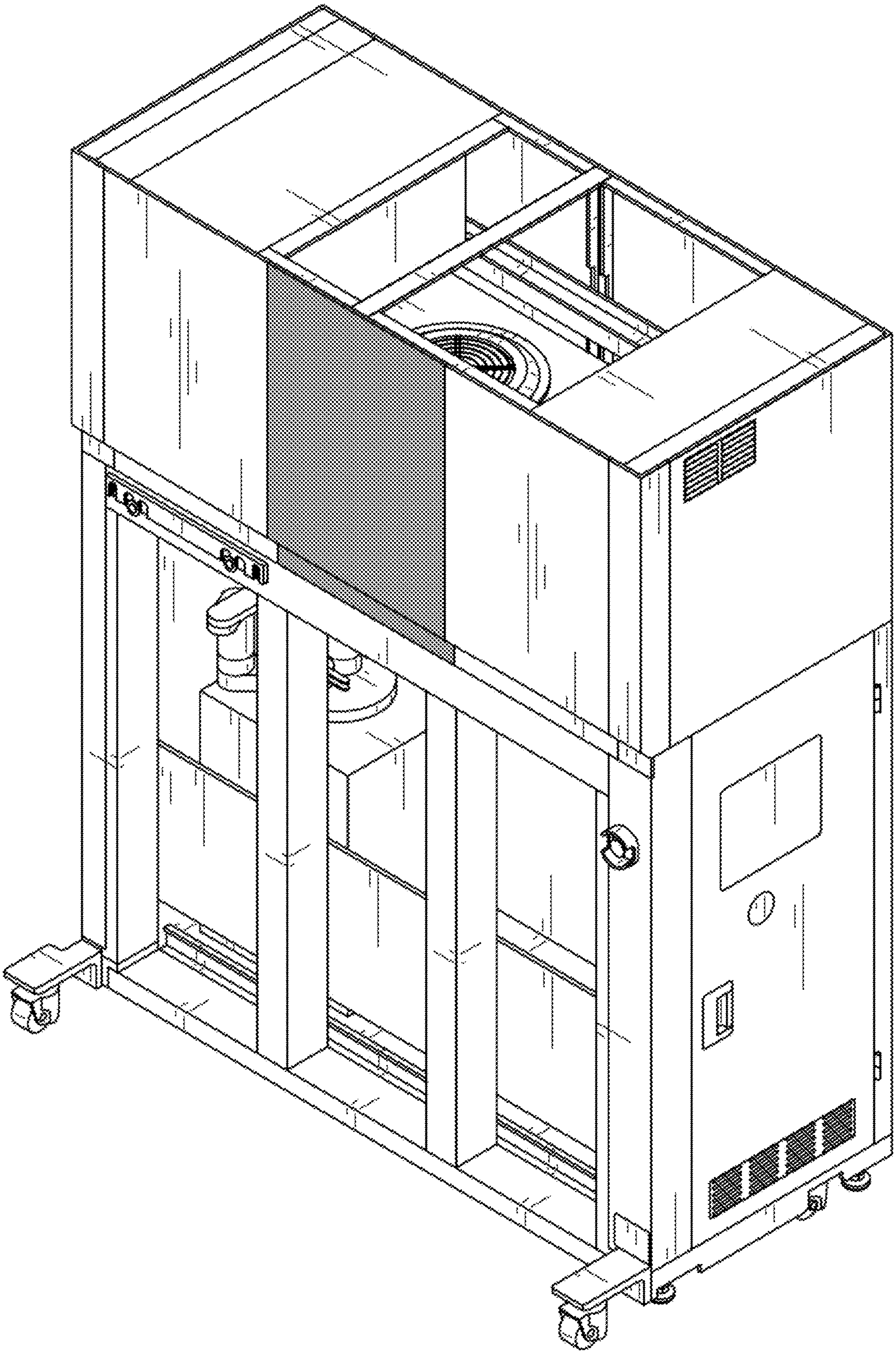

FIG. 1

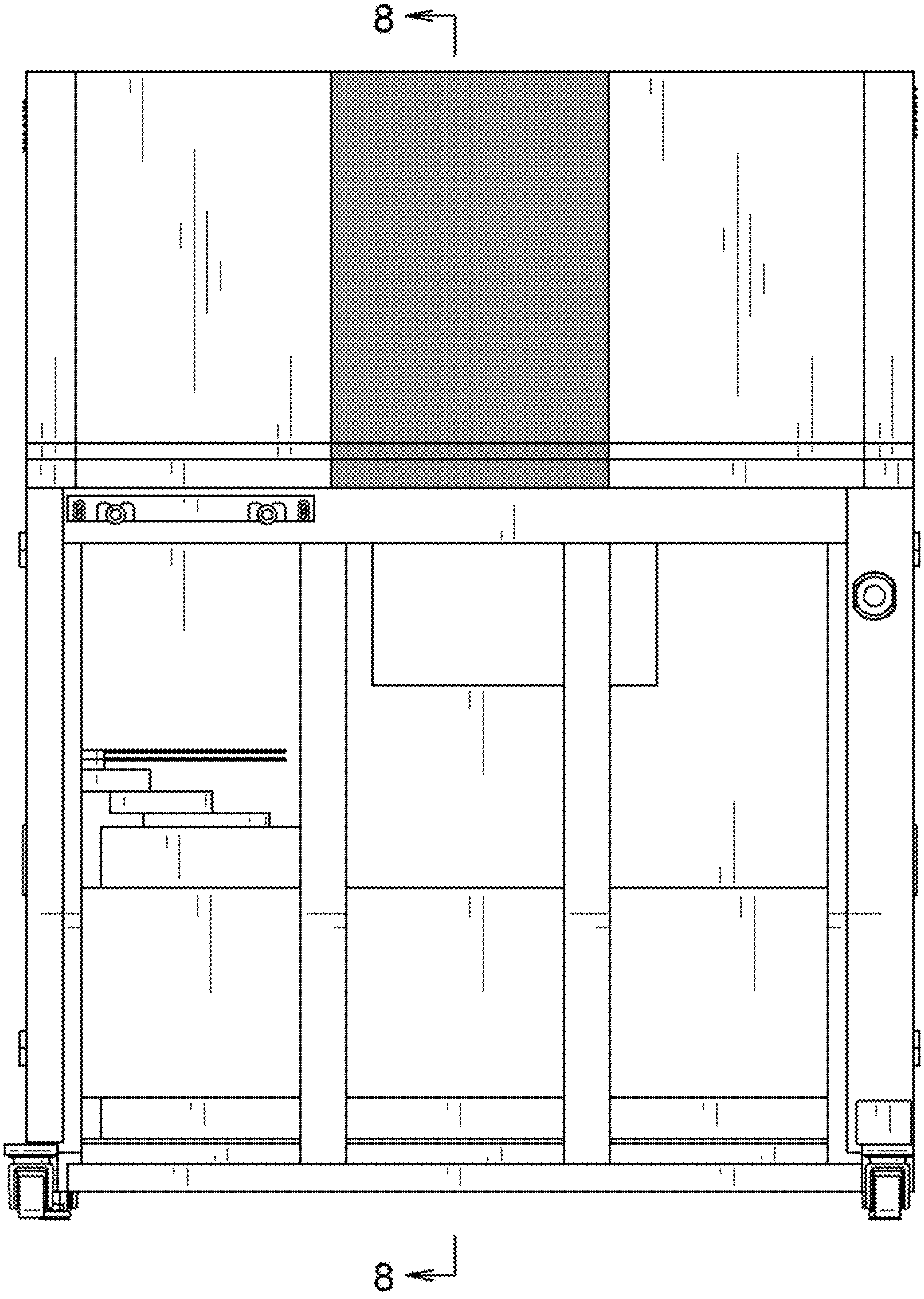

FIG. 2

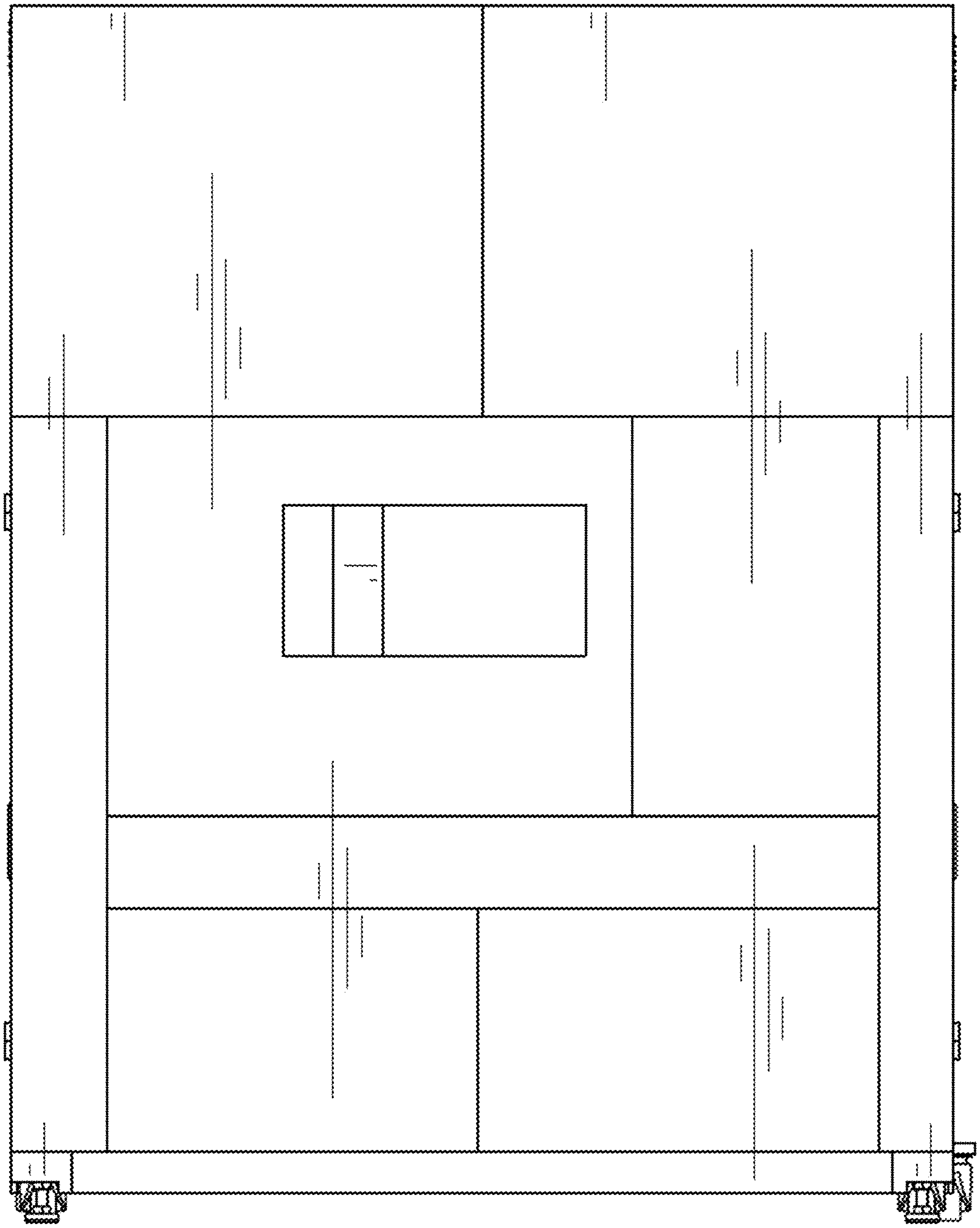

FIG. 3

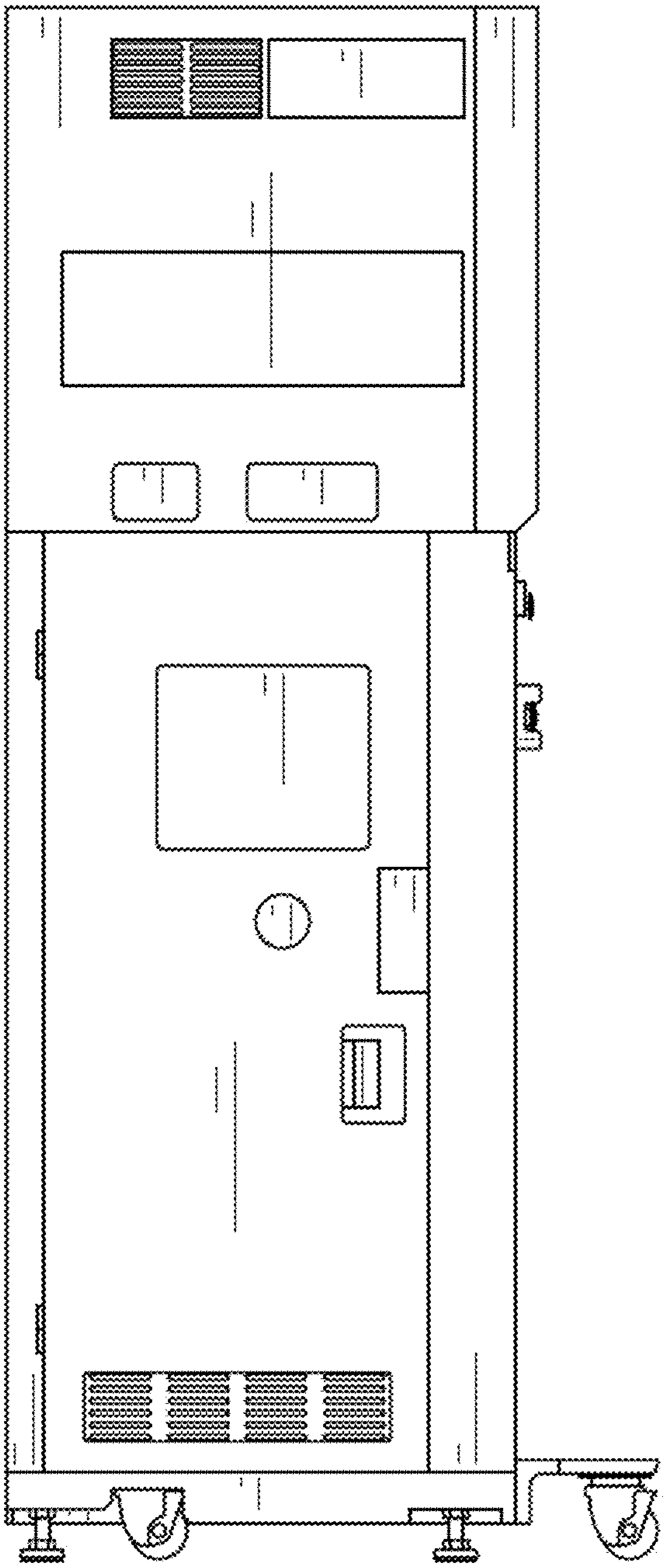

FIG. 4

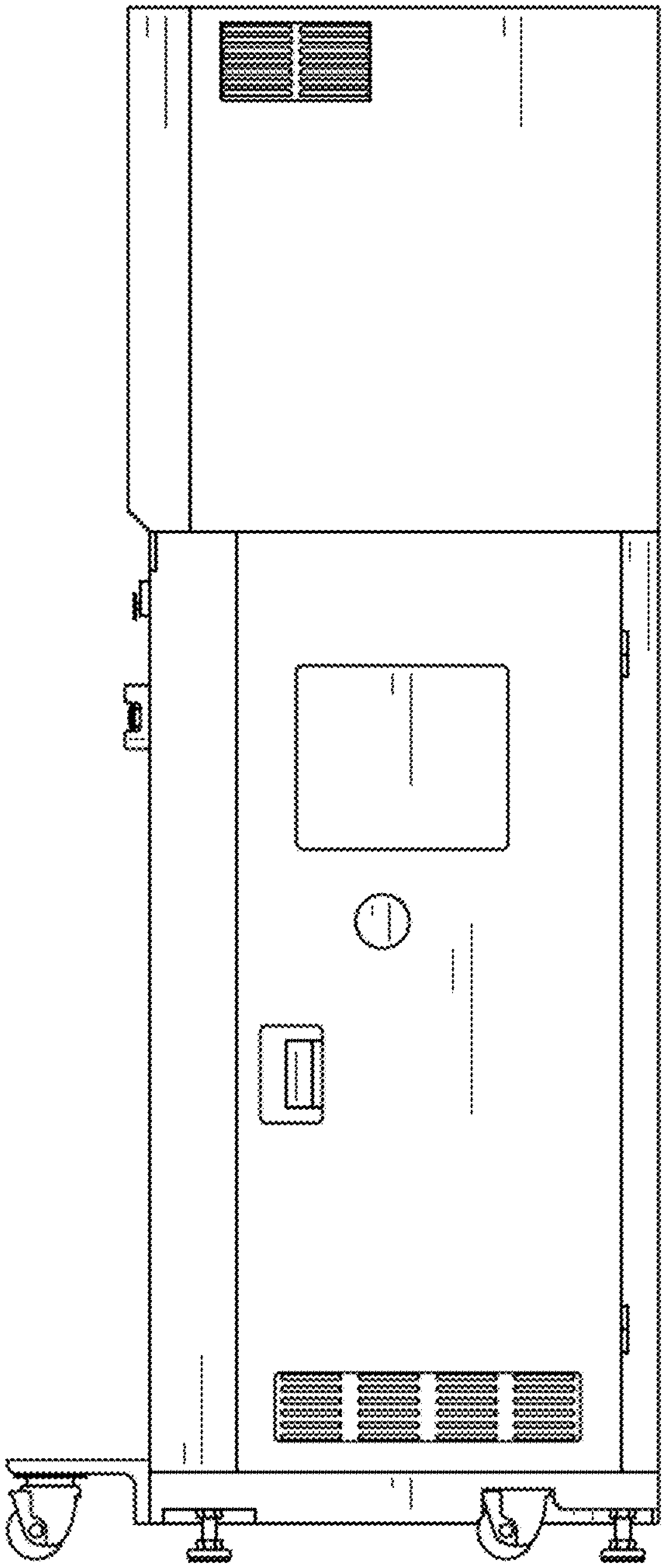

FIG. 5

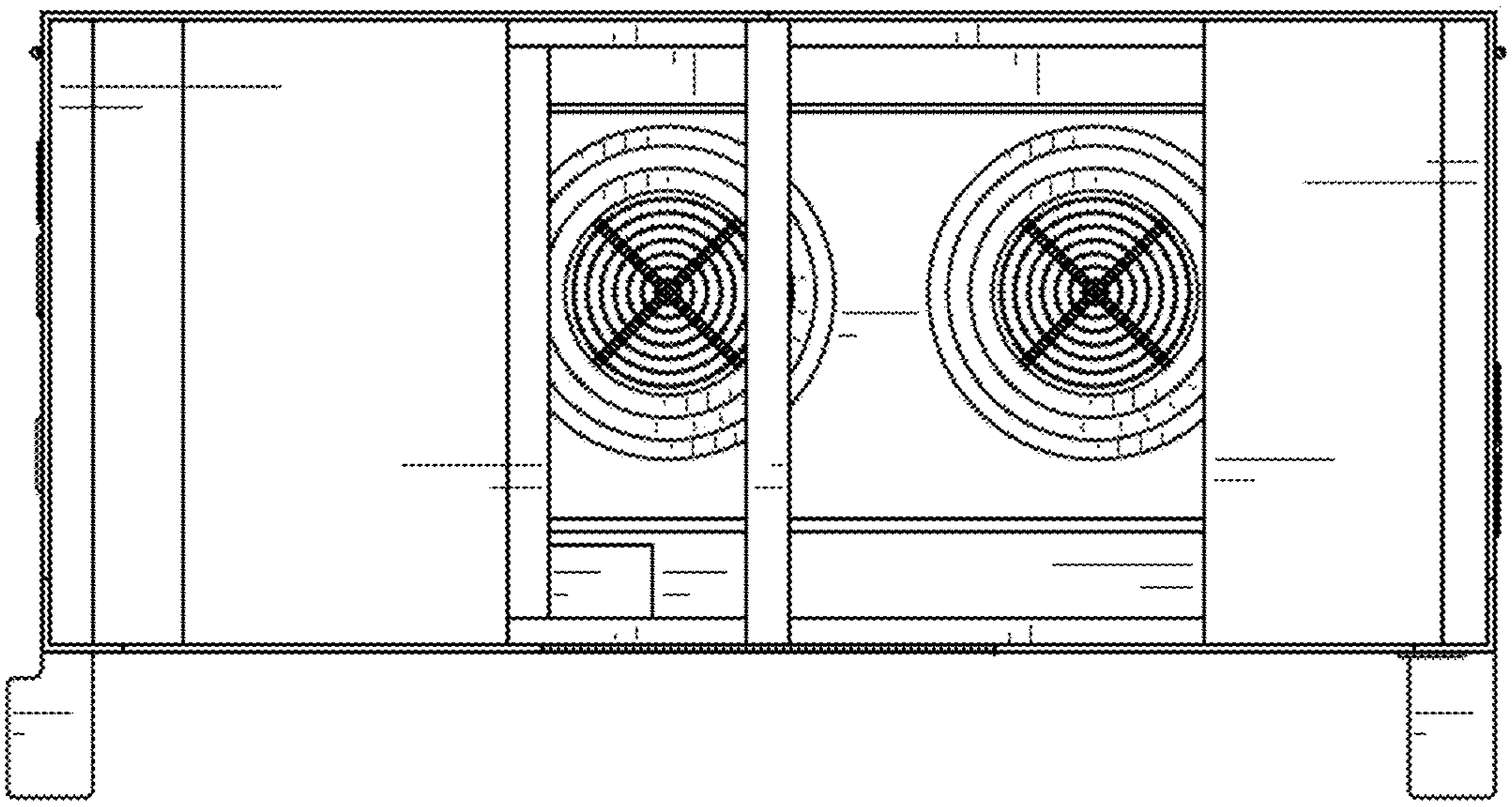

FIG. 6

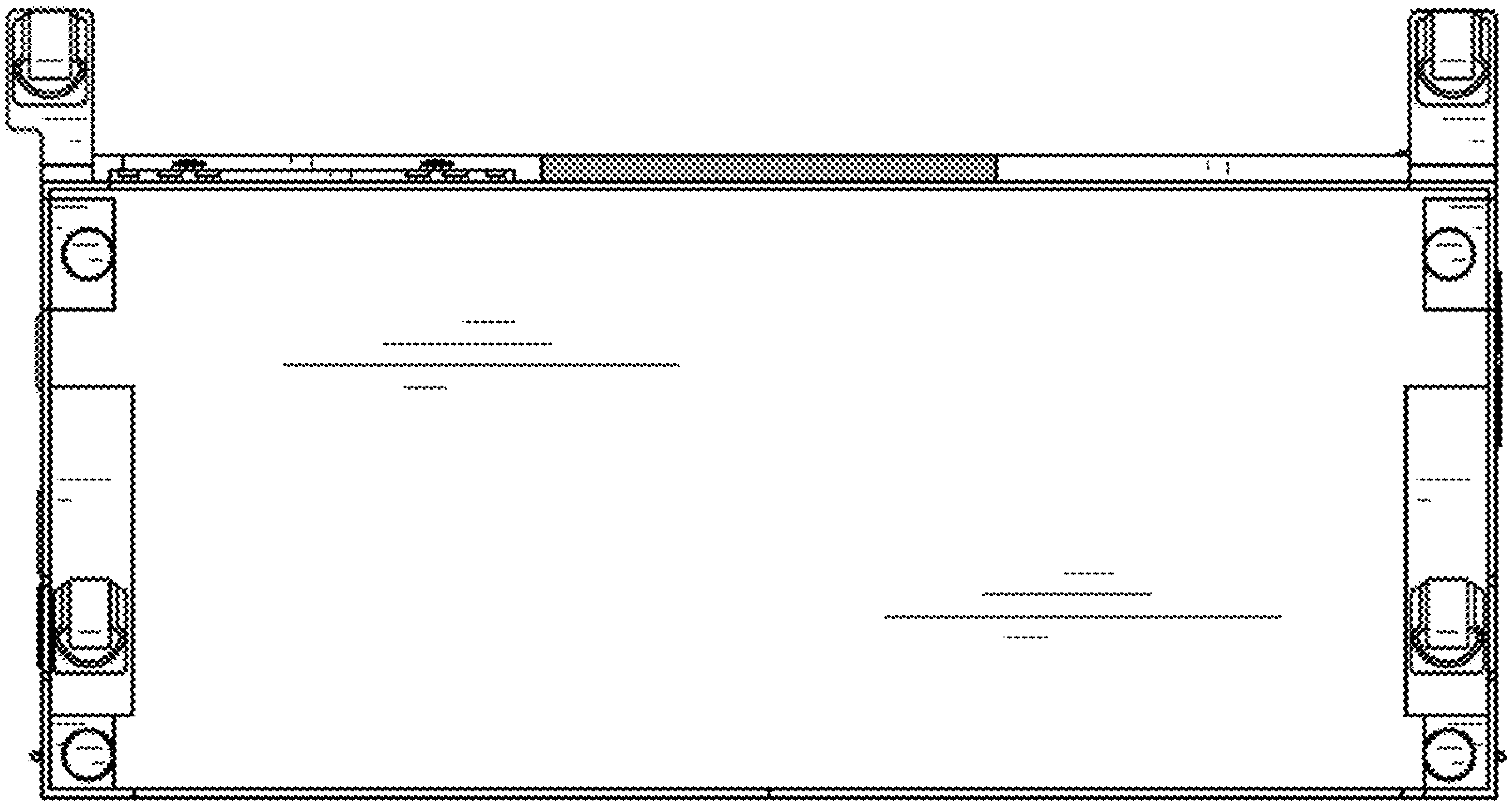

FIG. 7

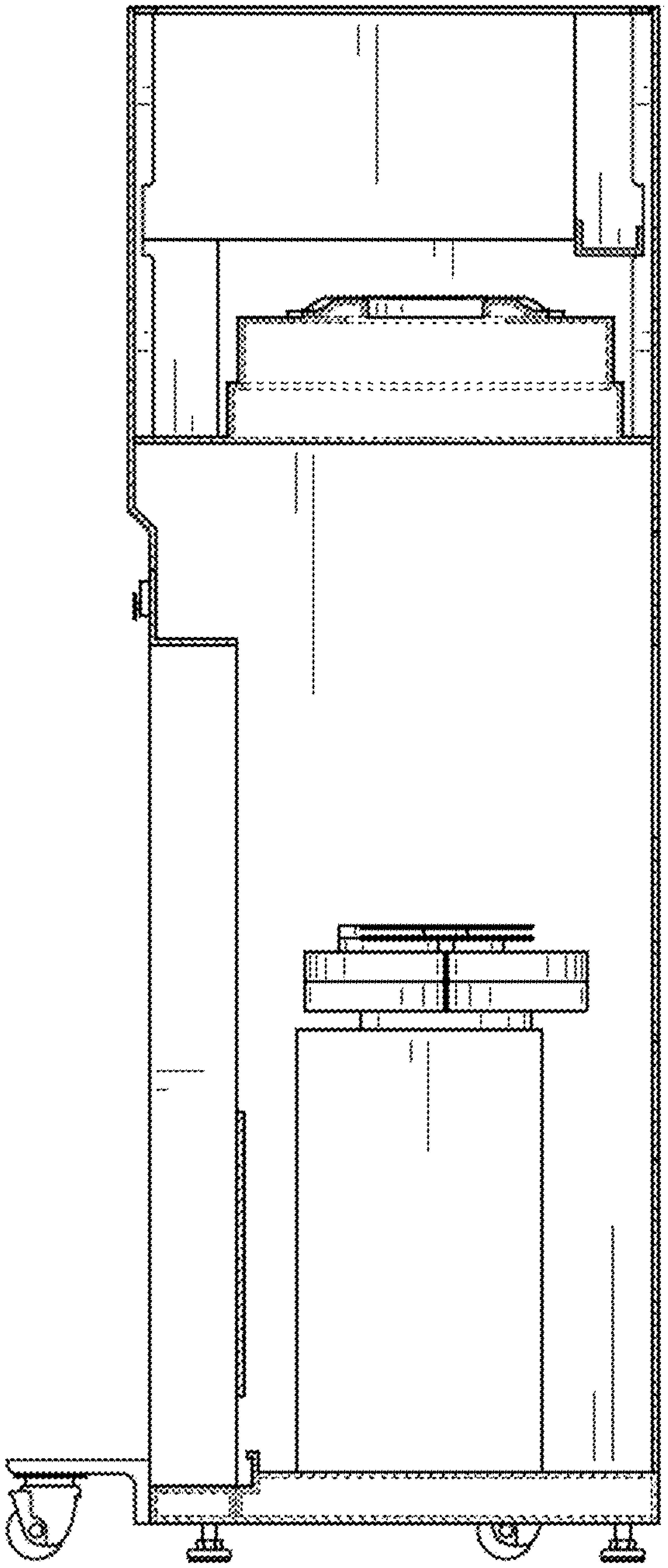

FIG. 8